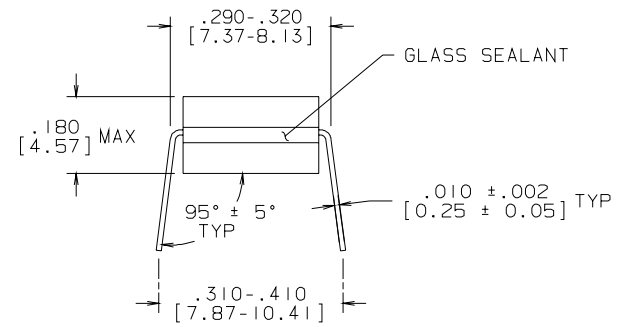
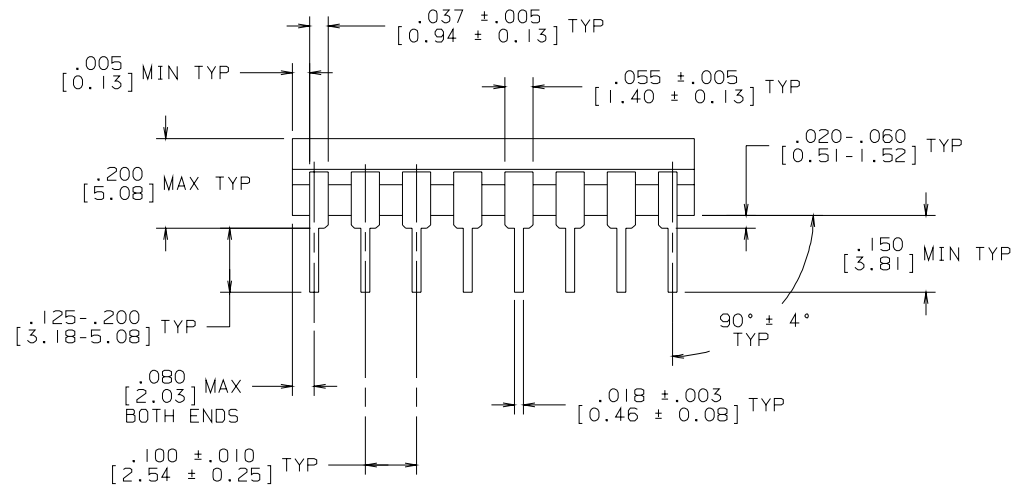
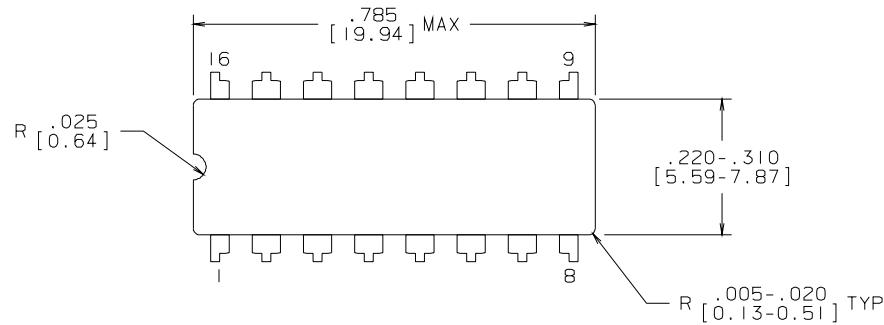


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
L	REVISE PER CURRENT STD; REDRAW	09996	09/15/93	TL/



MIL/AERO
CONFIGURATION CONTROL

MIL-M-38510
CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH TO BE 200 MICRONS / 5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
- JEDEC REGISTRATION M0-036, VARIATION AD, DATED 04/1981.

CONTROLLING DIMENSION: INCH

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRAWN T. LEQUANG	09/15/93	2900 Semiconductor Drive, Santa Clara, CA 95052-8090			
DFTG. CHK.		CERDIP (J), 16 LEAD			
ENGR. CHK.					
APPROVAL					
 INCH [MM]		SCALE N/A	SIZE B	DRAWING NUMBER MKT-J16A	REV L
		DO NOT SCALE DRAWING		SHEET 1 OF 1	